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5-3002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Akihisa HONGO et al.

Serial No. ~~NEW~~

10/017384

Filed December 18, 2001

Attn: Application Branch

Attorney Docket No. 2001-1846

SUBSTRATE PLATING METHOD AND
APPARATUS

(Rule 1.53(b) Divisional
of Serial No. 09/674,179,
Filed October 27, 2000)

1741
Valentine

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Prior to examination of the above-referenced U.S. patent application please amend the application as follows:

IN THE SPECIFICATION

Please amend the specification as follows:

Before line 4, on page 1, please insert the following:

A1 This is a Divisional Application of U.S. Patent Application Serial No. 09/674,179, which
is the national stage of PCT/JP99/02271, filed April 28, 1999.

now US 6,517,894, del

Please replace the paragraph beginning at page 4, line 19, to line 26, with the following rewritten paragraph:

A2 These objects and others will be attained by a method for plating a substrate having a surface with fine pits formed therein, the method comprising performing a first plating process by immersing the substrate in a first plating solution having a composition superior in throwing